



**Product Change Notification / RMES-02XBET158**

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**Date:**

02-Aug-2021

**Product Category:**

32-bit Microcontrollers

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 4407 Final Notice: Qualification of new lead frame design with Double ring Ag on die attach paddle (DAP) surface prep material for selected AT32UC3B0512, AT32UC3C2512C, AT32UC3C2128C, AT32UC3C2256C and AT32UC3C264C device families available in 64L TQFP (10x10x1mm) package using 295x295 mils lead frame paddle size at ANAP assembly site.

**Affected CPNs:**

[RMES-02XBET158\\_Affected\\_CPN\\_08022021.pdf](#)  
[RMES-02XBET158\\_Affected\\_CPN\\_08022021.csv](#)

**Notification Text:**

**PCN Status:** Final notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of new lead frame design with Double ring Ag on die attach paddle (DAP) surface prep material for selected AT32UC3B0512, AT32UC3C2512C, AT32UC3C2128C, AT32UC3C2256C and AT32UC3C264C device families available in 64L TQFP (10x10x1mm) package using 295x295 mils lead frame paddle size at ANAP assembly site.

**Pre and Post Change Summary:**

	Pre Change	Post Change
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Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)		Amkor Technology Philippine (P1/P2), INC. (ANAP)
	Wire material	AuPd	
Die attach material	3230		3230
Molding compound material	G700L		G700L
Lead frame material	C194		C194
Lead frame Paddle size	295x295 mils	224x240 mils	295x295 mils
Lead frame die attach paddle (DAP) surface prep material	Double Ring Ag	Ring Ag	Double Ring Ag
	See Pre and Post Change attachment for lead frame comparison		

**Impacts to Data Sheet:** None

**Change Impact:** None

**Reason for Change:** To improve manufacturability by qualifying new lead frame design with Double ring Ag on die attach paddle (DAP) surface prep material using 295x295 mils lead frame paddle size

**Change Implementation Status:** In Progress

**Estimated First Ship Date:**

August 30, 2021 (date code: 2136)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	August 2021				
	Workweek	32	33	34	35
Qual Report Availability	X				
Final PCN Issue Date	X				
Estimated Implementation Date					X

**Method to Identify Change:** Traceability code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History: August 02, 2021:** Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

[PCN\\_RMES-02XBET158\\_Pre and Post Change\\_Summary.pdf](#)  
[PCN\\_RMES-02XBET158\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

AT32UC3B0512-A2UT  
AT32UC3B0512-A2UR  
AT32UC3C2512C-A2ZT  
AT32UC3C2128C-A2ZT  
AT32UC3C2256C-A2ZT  
AT32UC3C2128C-A2UT  
AT32UC3C2256C-A2UT  
AT32UC3C2512C-A2UT  
AT32UC3C264C-A2UT  
AT32UC3C2128C-A2UR  
AT32UC3C2256C-A2UR  
AT32UC3C2512C-A2UR  
AT32UC3C264C-A2UR  
AT32UC3C2512C-A2ZR  
AT32UC3C2128C-A2ZR  
AT32UC3C2256C-A2ZR